



Compute, Memory,  
and Storage

# New Memories for Inference & General- Purpose Compute

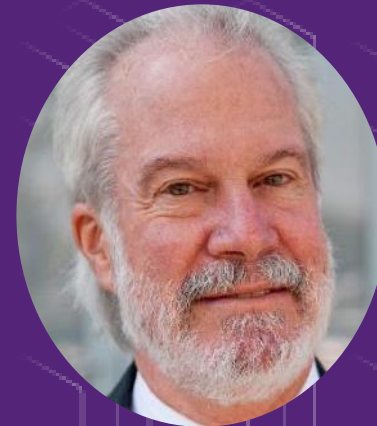
Live Webinar

January 20, 2026

12:00 Noon PT/ 3:00 pm ET



Arthur Sainio,  
SNIA PM SIG  
Chair



Jim Handy,  
Objective  
Analysis



Tom Coughlin,  
Coughlin  
Associates



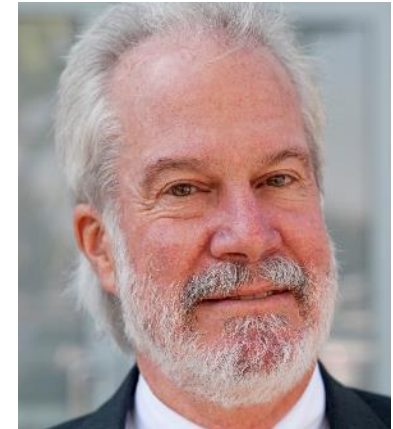
# Introductions



**Arthur Sainio**  
*Moderator*  
Co-Chair,  
SNIA Persistent Memory  
Special Interest Group



**Tom Coughlin**  
*Presenter*  
President, Coughlin Associates  
Past President, IEEE



**Jim Handy**  
*Presenter*  
President,  
Objective Analysis



# The SNIA Community



**200**  
industry leading  
organizations



**2,000**  
active contributing  
members



**50,000**  
IT end users & storage  
pros worldwide

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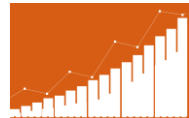
The industry leading member companies of the SNIA Compute, Memory, and Storage Community support the industry drive to combine processing with memory and storage, and to create new compute architectures and software to analyze and exploit the explosion of data creation over the next decade.

## What We Do



### Engage and Educate

- ✓ Computational Storage
- ✓ Persistent Memory
- ✓ PM and SSD Performance
- ✓ Emerging Memories
- ✓ Smart Data Accelerator
- ✓ Solid State Drives
- ✓ Solid State Systems
- ✓ SSD Form Factors



### Accelerate Standards

- ✓ Computational Storage Architecture & Programming Model
- ✓ Computational Storage API
- ✓ NVM Programming Model
- ✓ Smart Data Accelerator Interface
- ✓ Solid State Storage Performance Test Specifications
- ✓ SSD Form Factor Specifications

## How We Do It



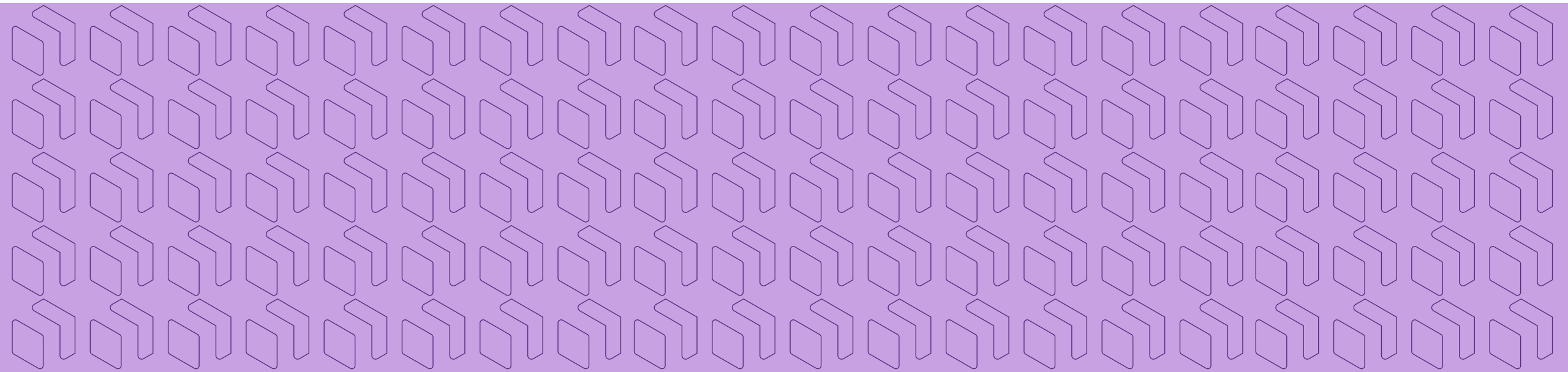
### Propel Technology Adoption

- ✓ Persistent Memory Programming Workshops
- ✓ SSD Form Factors Explained
- ✓ Computational Storage, Memory, and Solid State Drive Demonstrations at live and online technology events
- ✓ Interactive Webinars with Technology Industry Experts
- ✓ Videos on the SNIA Video YouTube Channel

# Outline

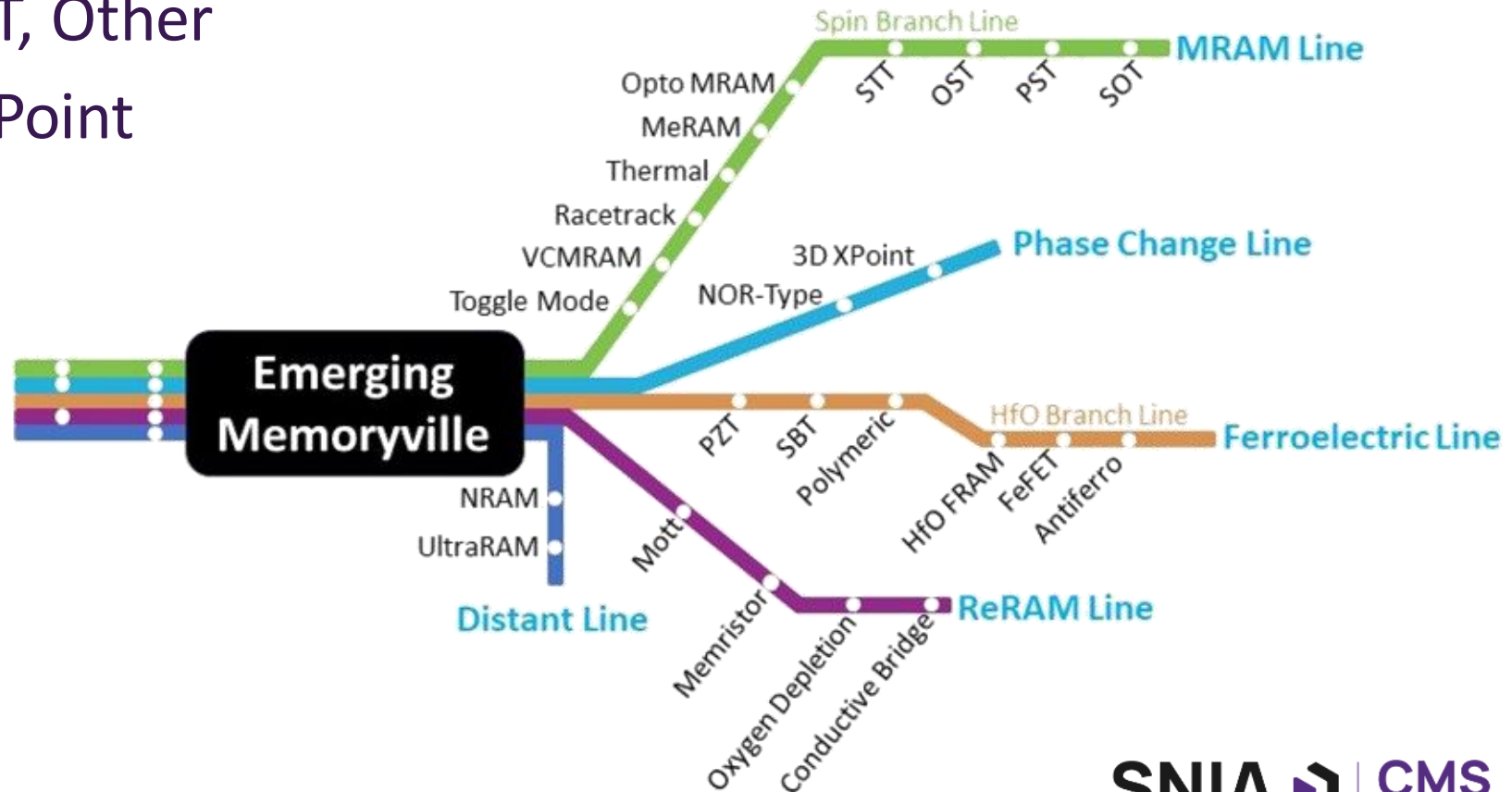
- New Memory Technology Overview
- Why Now?
- Compute-In-Memory
- Persistence in Standard Architectures
- CXL: An Enabler
- Market sizing
- Q & A

# New Memory Technologies



# New Memory Technology Overview

- Magnetic: MRAM, STT, SoT, etc.
- Resistive: Conductive Bridge, Oxygen Vacancy
- Ferroelectric: FRAM, FeFET, Other
- Phase Change: PCM, 3D XPoint
- Other Types

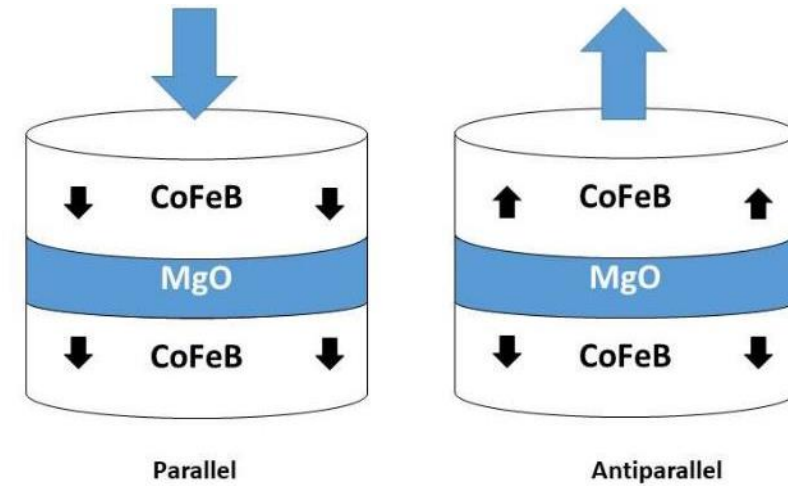


# All New Memories Share Common Attributes

- 1-transistor cell
- Nonvolatile
- High-speed write
- Write-in-place
- Better scaling limits
- Improved endurance

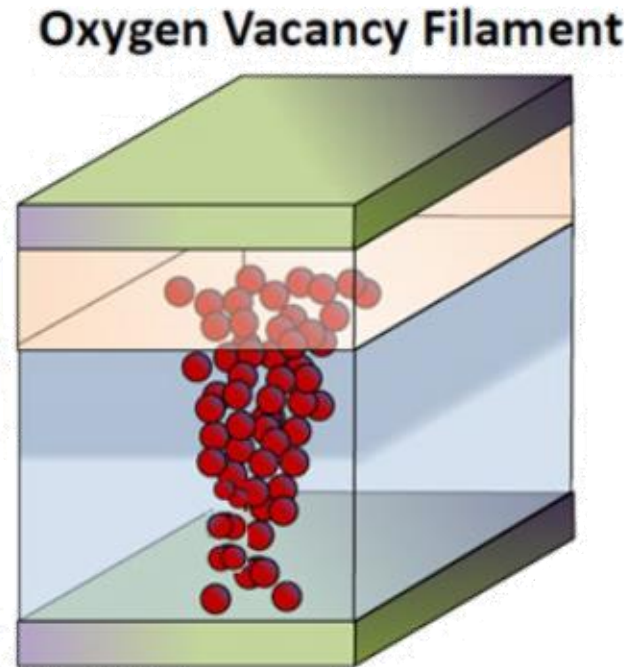
# MRAM

- In volume as embedded and discrete versions
  - Replacing NOR flash in embedded applications
- **Strengths**: Fast, low power, relatively small cell size, wide range, radiation-tolerant
- **Weaknesses**: Requires new materials (well understood), large program currents, magnetic sensitivity, MLC difficult
- **Variants**: In-Plane Toggle, Perpendicular, STT, SOT, MeRAM...
- **Suppliers/Researchers**: Everspin, TSMC, Samsung, GlobalFoundries, Others
- **Outlook**: Well-established, broad support, in leading position



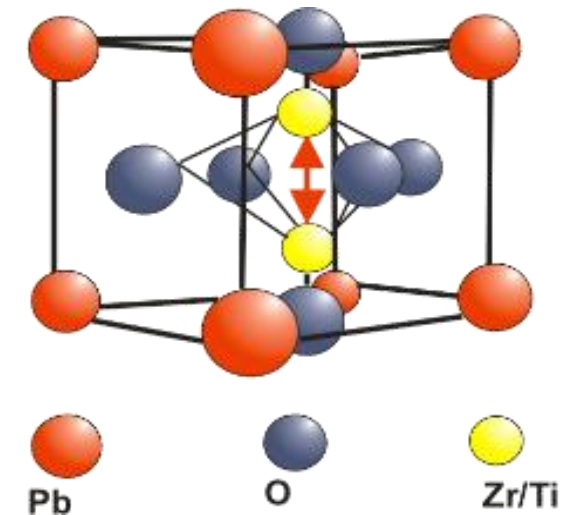
# ReRAM

- ✧ In limited production as embedded memory
- ✧ **Strengths**: Can be made without new materials, radiation-tolerant,
- ✧ **Weaknesses**: Selector challenge,
- ✧ **Variants**: Oxygen Vacancy, Conductive Bridge, (Memristor)
- ✧ **Suppliers/Researchers**: Weebit, Fujitsu, Nuvoton, Renesas, TSMC, UMC, Winbond, Others
- ✧ **Outlook**: Has the potential to rise above others in the long run.



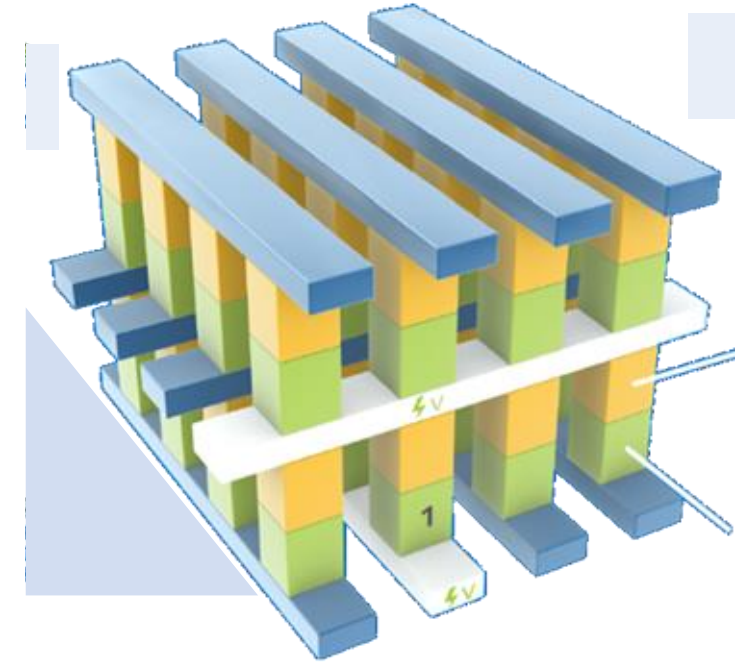
# FRAM

- Very high production volume in some forms, but low wafer run rate
- Strengths:** Extremely low write energy, high speed,  $10^{15}$  endurance, could use volume HfO process
- Weaknesses:** Current volume process doesn't shrink & attacks Silicon, new process struggling to reach production
- Variants:** PZT, SBT, HfO
- Suppliers/Researchers:** Infineon, TI, IBM, FMC, Others
- Outlook:** A production process breakthrough could change the market



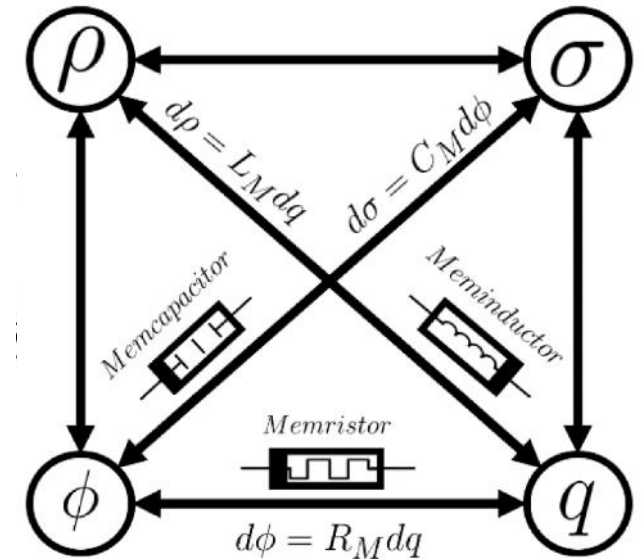
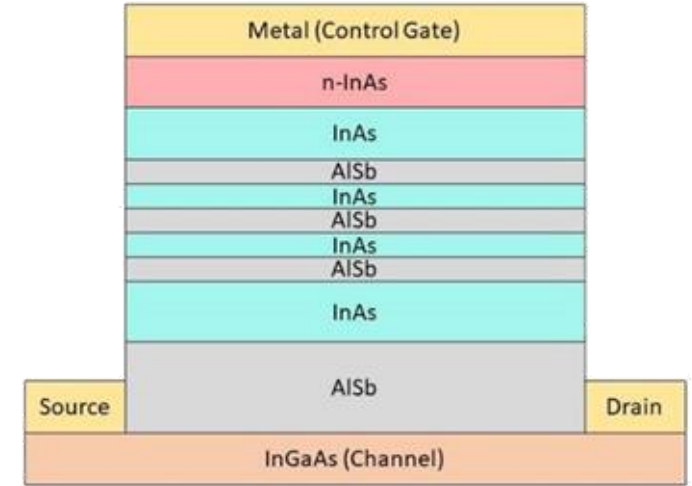
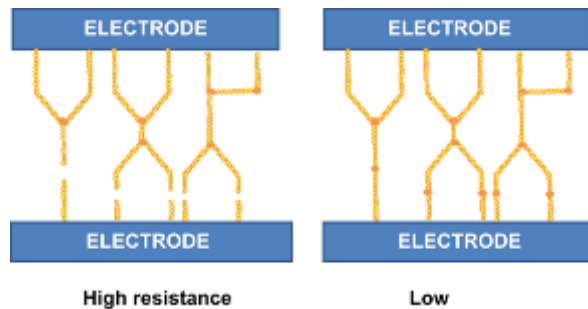
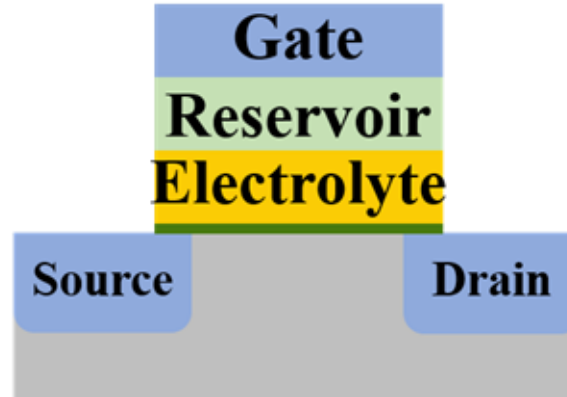
# PCM

- One embedded processor and a failed high-volume product
- Strengths:** Well-understood, matches selector material, small cell
- Weaknesses:** High-energy write, challenging materials, thermal sensitivity
- Variants:** Thermal vs. bulk change
- Suppliers/Researchers:** Intel, Micron, Sandisk, IBM, others
- Outlook:** No major commercialization efforts
  - Intel's learning not being used

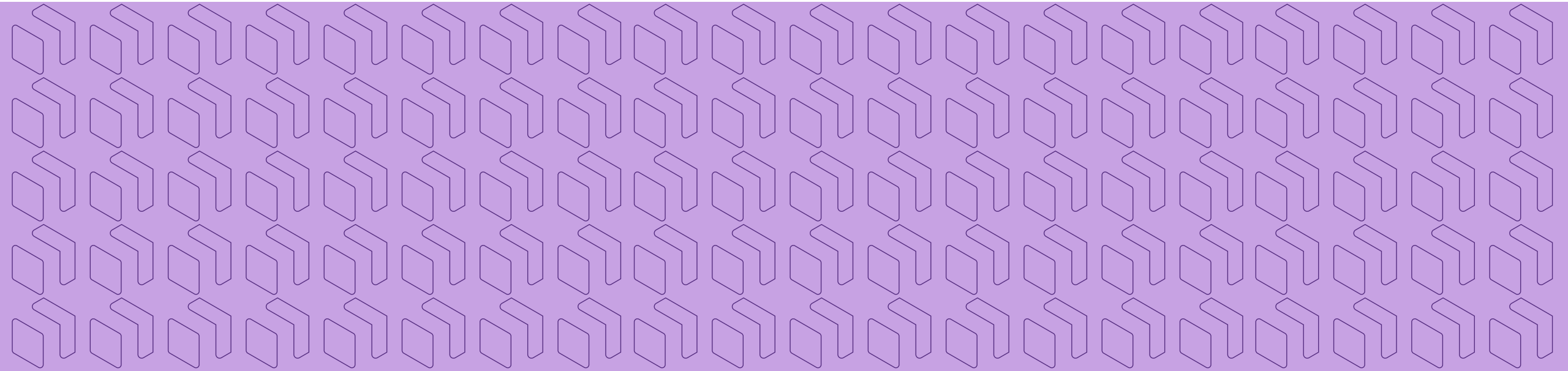


# No Shortage of New Ideas

- Resonant Tunneling
- Mott Memories
- Nanotubes
- Quantum dots
- Memcapacitor
- Meminductor
- Polymeric
- Electrochemical
- Selector-Only Memory
- DNA



# Why Now?

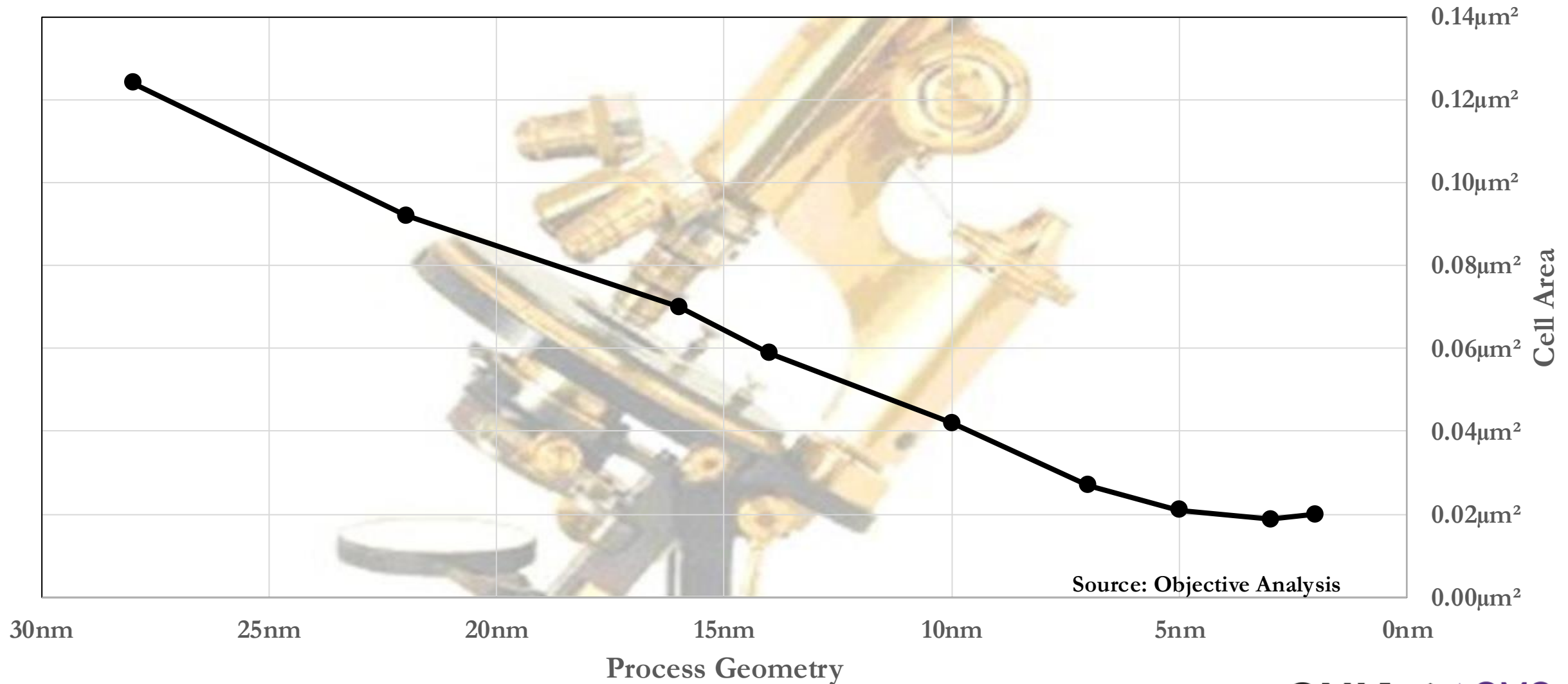


# New Memory Growth Drivers

- ❏ End of NOR scaling
  - ❏ Embedded memories require a new technology after 28nm
  - ❏ Lack of NOR is limiting to MCUs, ASICs, etc.
- ❏ SRAM scaling slowdown
  - ❏ Lithographic scaling benefits are being limited by SRAM
  - ❏ This weakens cost improvements for MPUs, FPGAs, & other SoCs
- ❏ DRAM capacitor issues
  - ❏ DRAM capacitors went 3D in the 1990s. Few remaining shrink options
  - ❏ The largest memory market is facing trouble

# SRAM No Longer Scales with Process

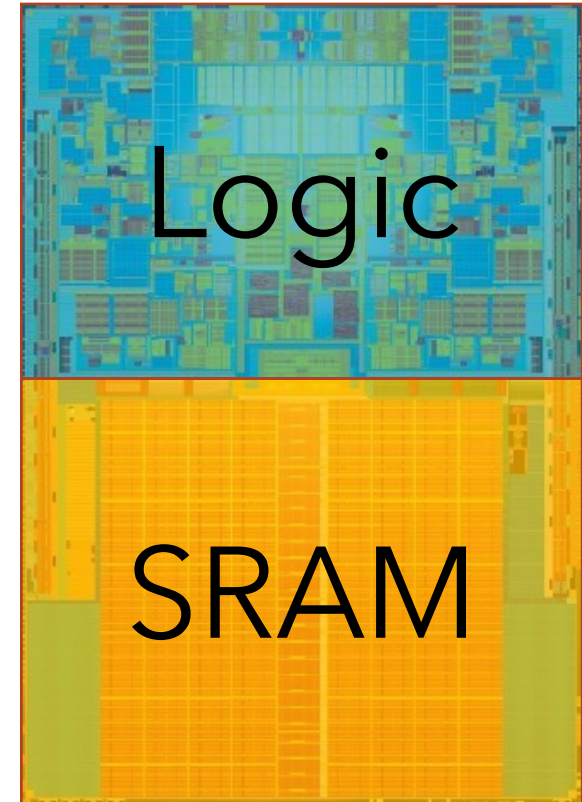
## SRAM Cell Area vs. Process



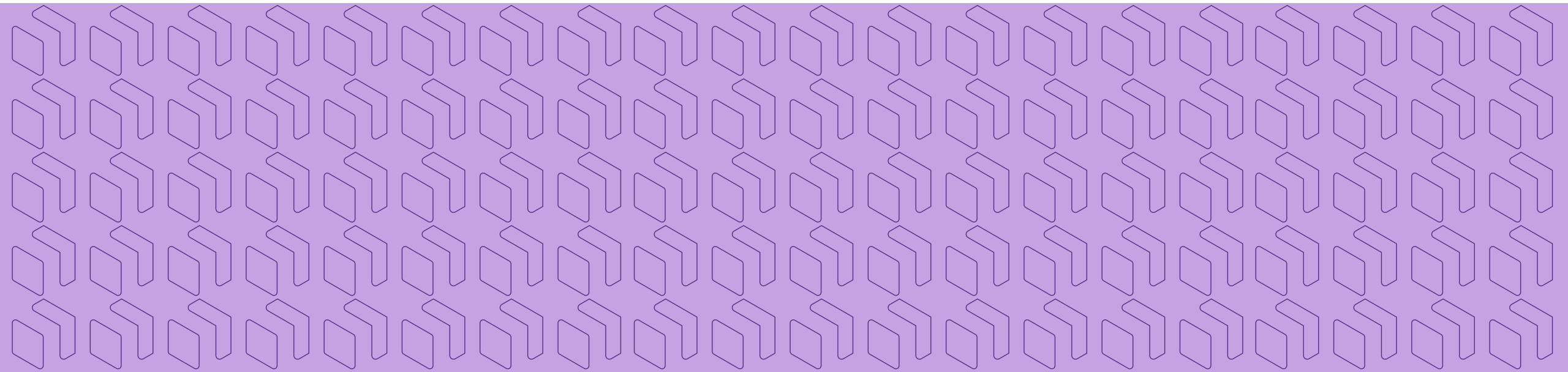
# Why Chiplets Will Use New Memories

- Embedded NOR has stopped shrinking
- Embedded SRAM is running into trouble
- New Memories use different processes
  - These processes can shrink in step with logic shrinks
- Embedded SRAM is the most expensive SRAM on the planet!
  - But it's fast
    - But fast can be traded off against big
    - A big slow off-chip memory chiplet can be really cheap

- Remove the SRAM to cut this chip's cost >50%!**



# Compute-In-Memory



# Compute-In-Memory Types

## ▣ Digital

- ▣ Compute “In” Memory (at the bit)
  - ▣ TCAM is one example
- ▣ Compute “Near” Memory (outside the array)

## ▣ Analog

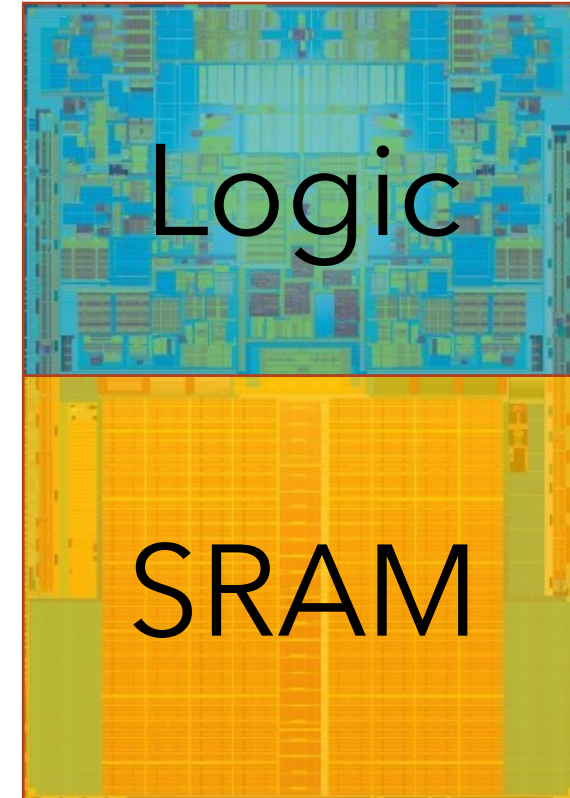
- ▣ Analog Neural Nets (ANN)

## ▣ Lots of names

- ▣ Compute-In-Memory (CIM)
- ▣ In-Memory Compute
- ▣ Processor-In-Memory (PIM)

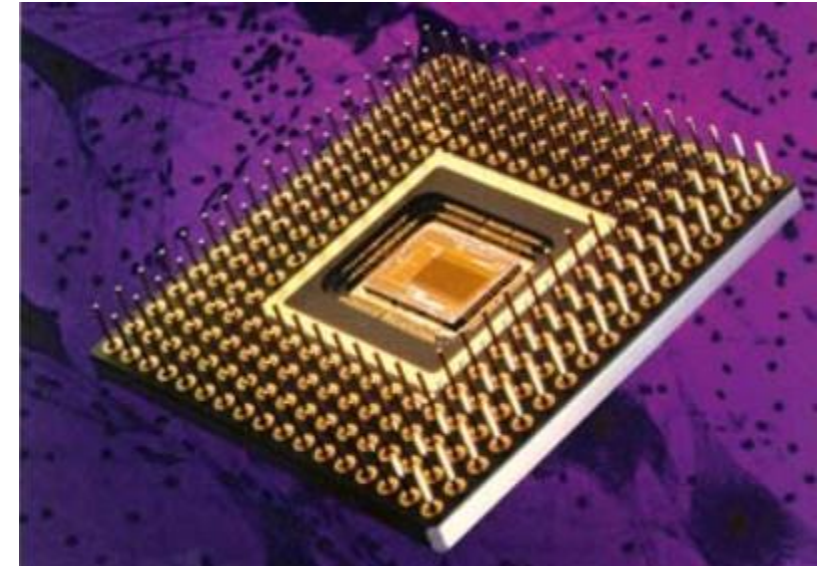
# Guess What? Standard CPUs are CIM!

- Processor with on-chip SRAM
- SRAM with on-chip processor
- Very high speed internal data movement

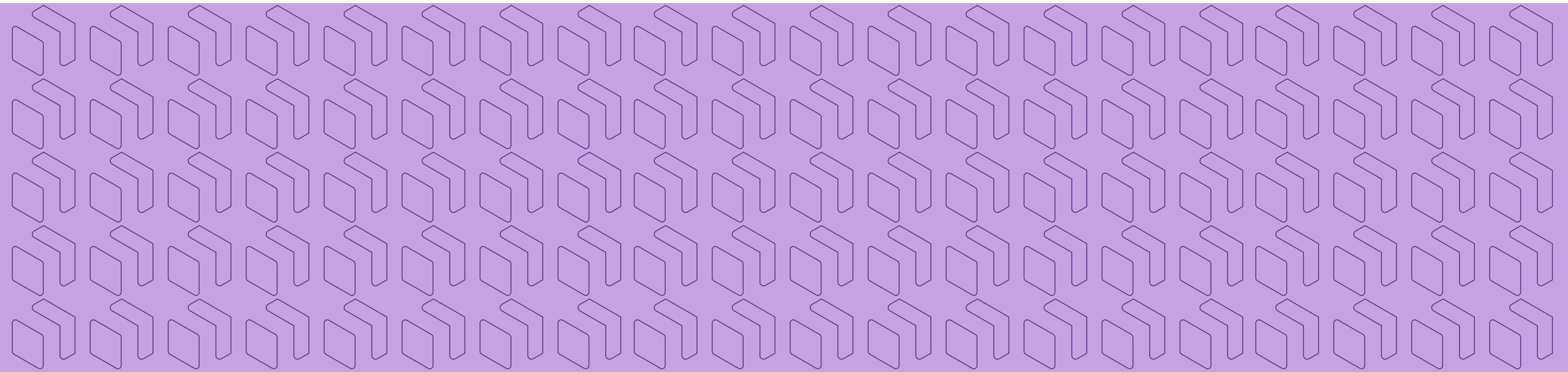


# Analog Neural Networks

- Neural nets are great for endpoint applications
  - Low energy consumption
  - “Fast enough” performance
  - Low die complexity ► low cost
- There are drawbacks
  - No clear leadership or standards
  - Limited functionality
  - Very little software support
- Digital neural nets should stick around



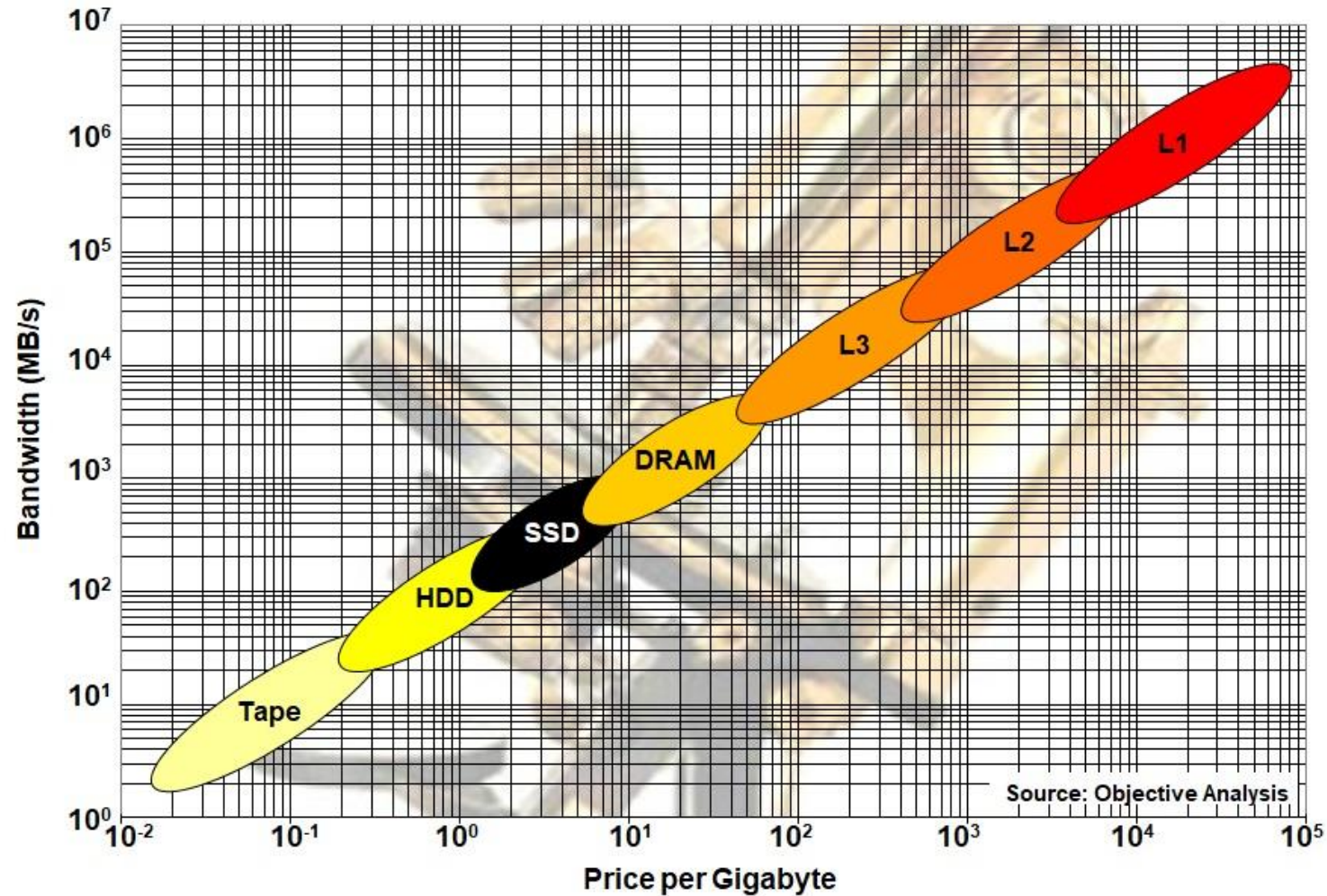
# Persistence in Standard Architectures



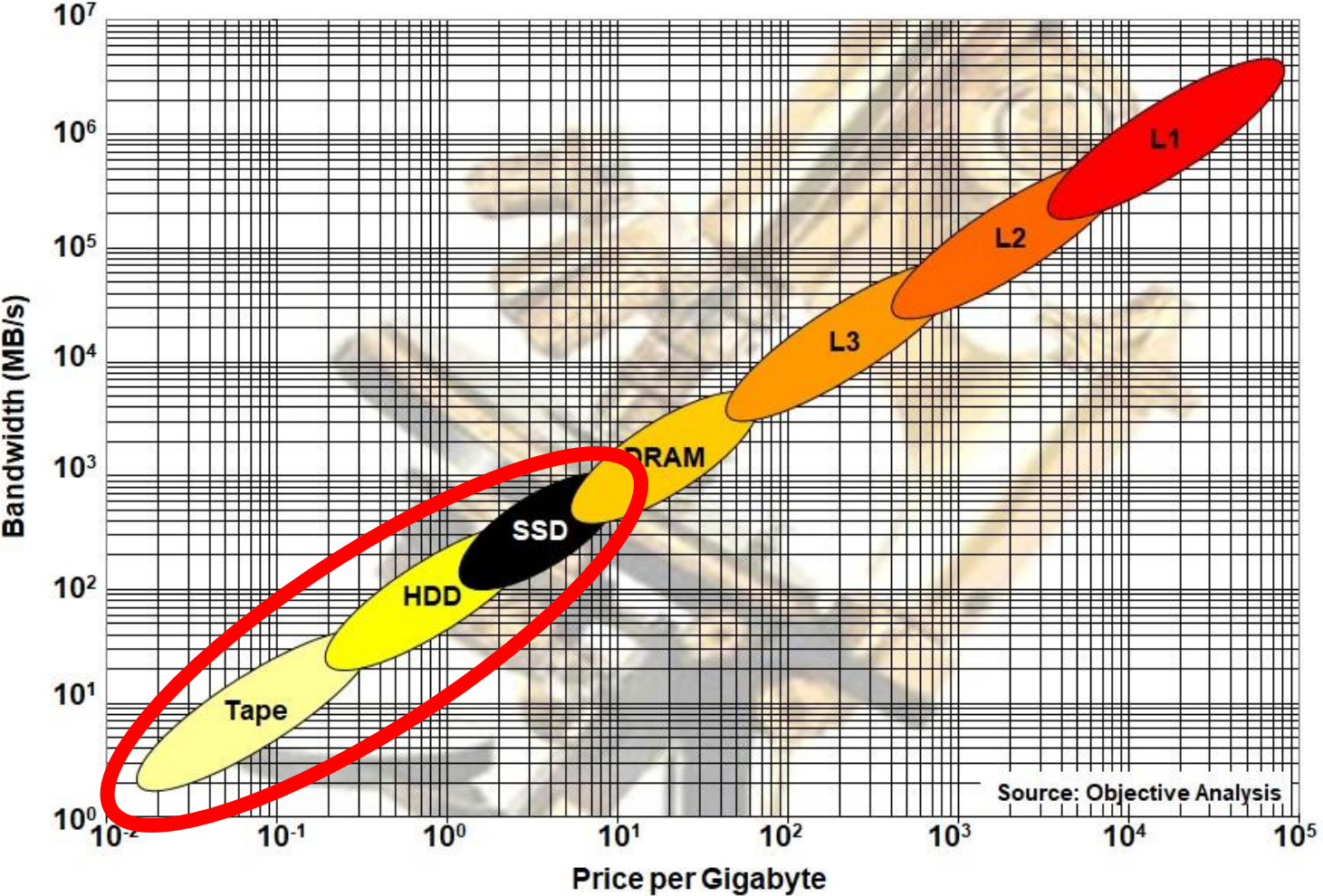
# Caches Are Headed Toward Persistence

- Use a new memory technology for cache
  - Smaller cell than SRAM
  - Continues to scale with process geometry
  - Slow and big caches can substitute for fast and small
- Put the slower caches onto chiplets
  - Cache chiplets can be made on a memory wafer
    - New memories are again a good option
  - Logic on foundry logic wafer
- Both of these solutions are nonvolatile/persistent
  - All new memory technologies scale
  - All new memory technologies are persistent

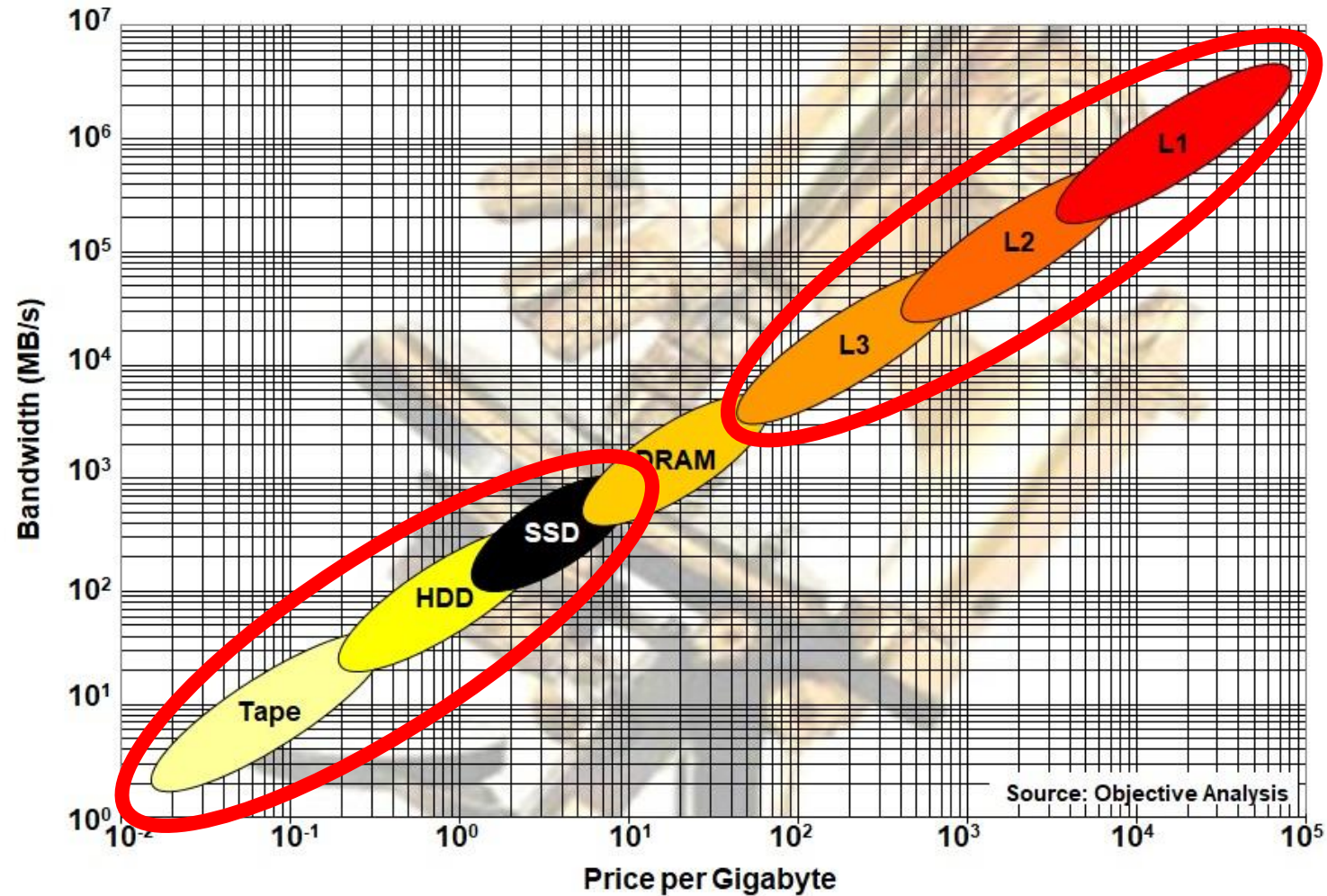
# In the End, Nearly Everything Becomes Persistent



# In the End, Nearly Everything Becomes Persistent



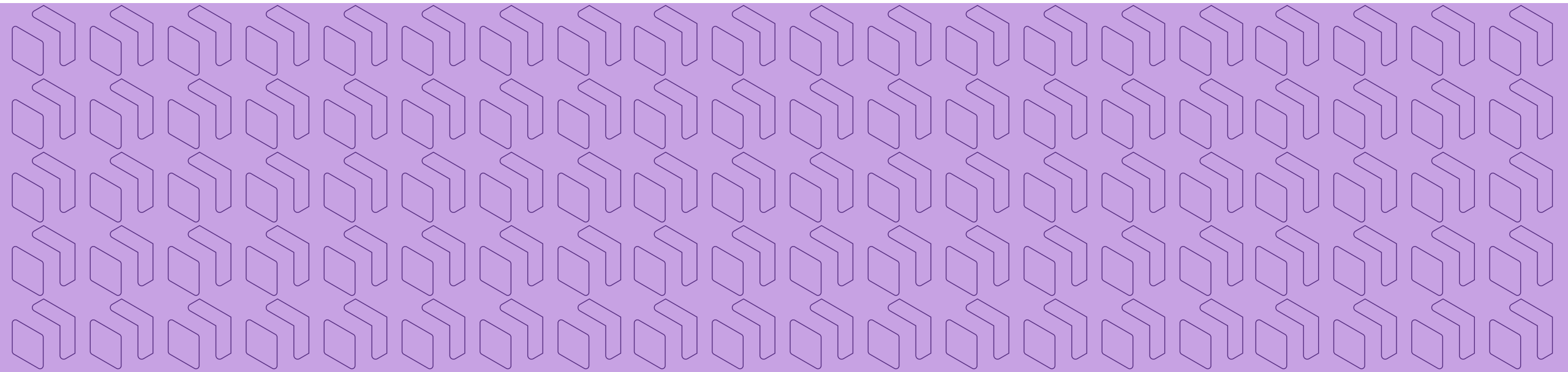
# In the End, Nearly Everything Becomes Persistent



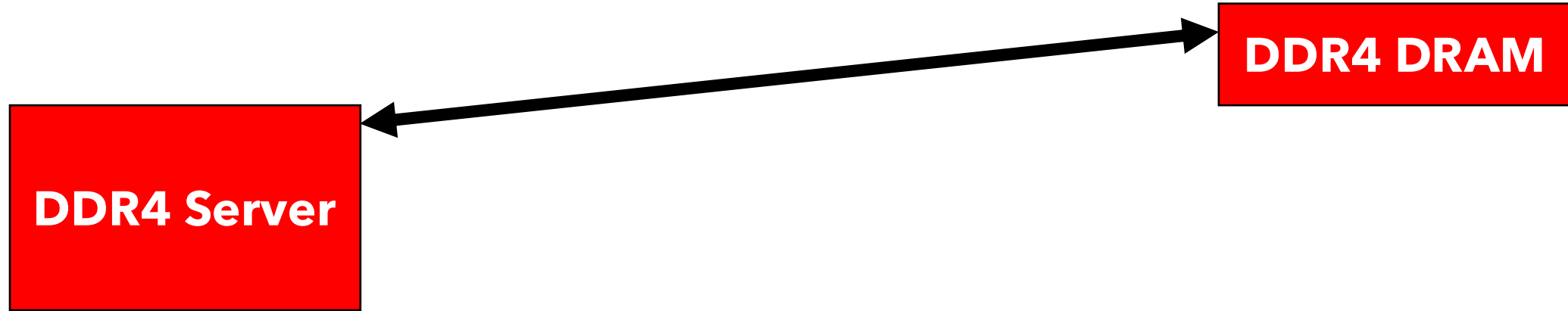
# Enablers Are Falling Into Place

- SNIA Nonvolatile Memory Programming Model is here now
  - Limited application programs from Oracle & SAP
  - Designed to support future persistent architectures
- CXL supports varying memory speeds
  - Processors can communicate with DRAM, MRAM, ReRAM, etc.
- UCle is based on CXL

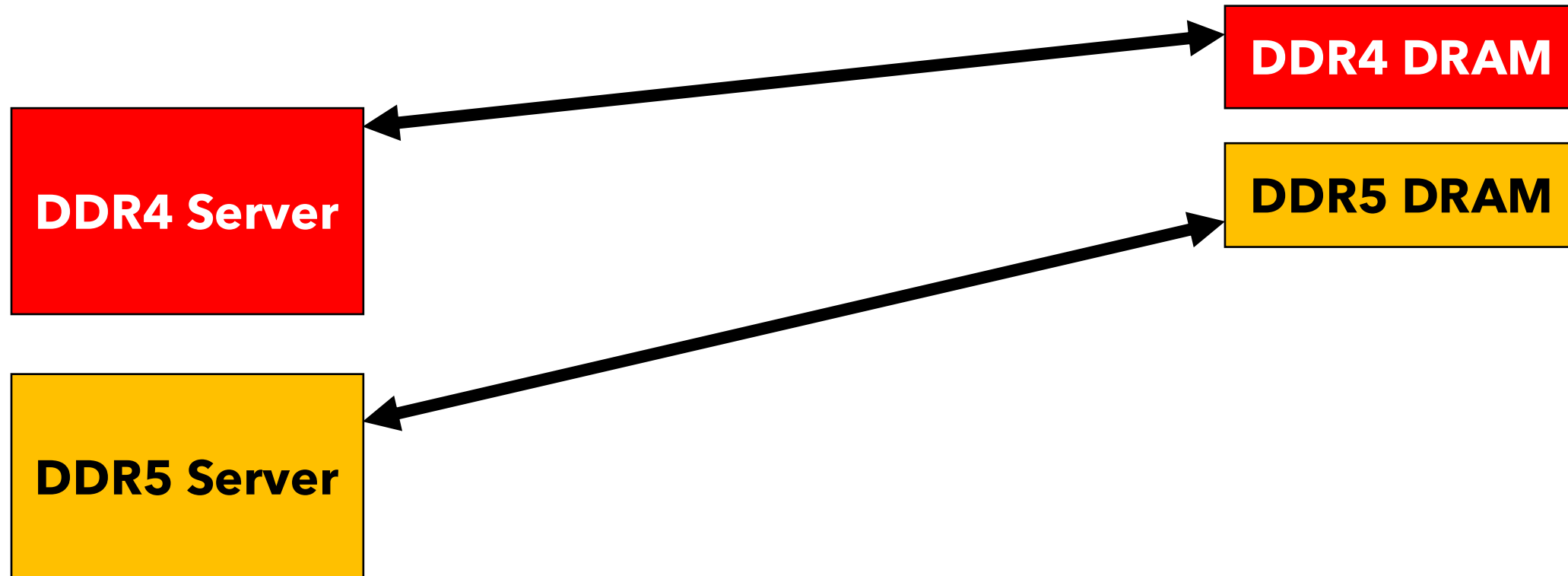
# CXL: An Enabler



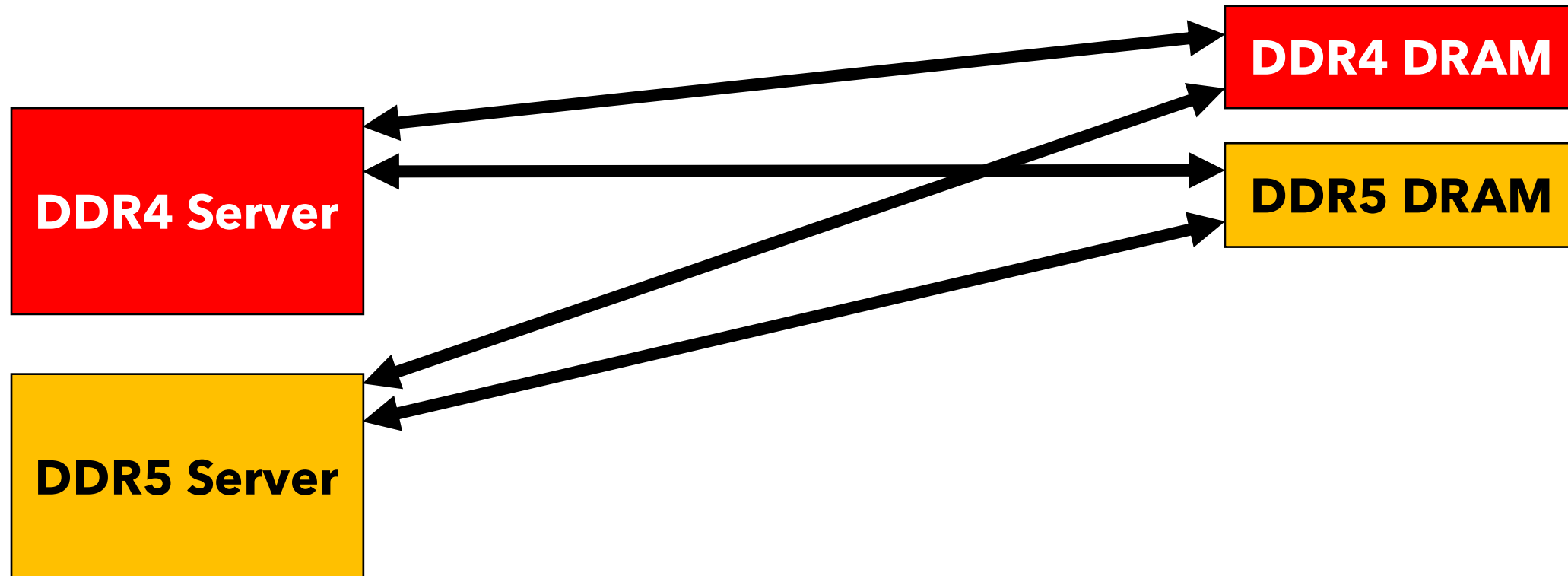
# CXL Supports Any Memory, Volatile or Persistent



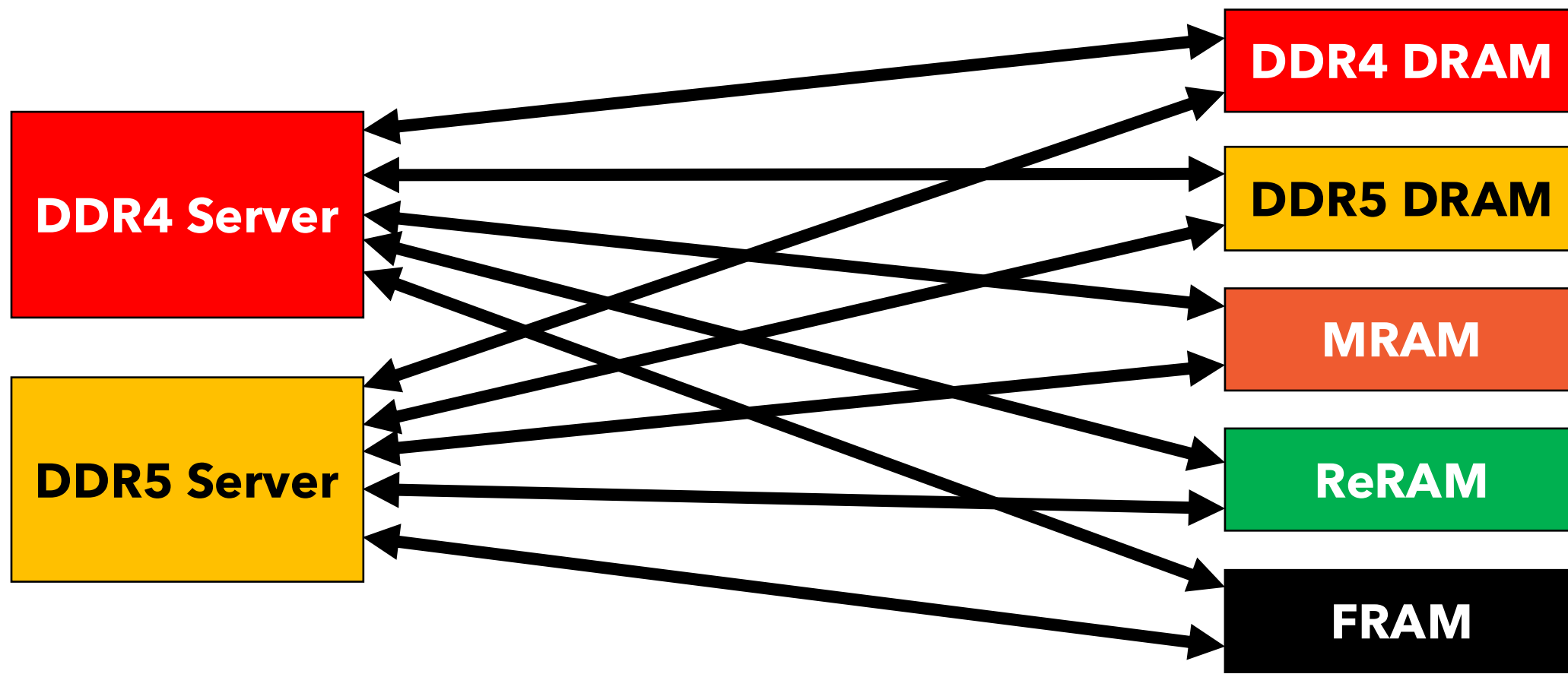
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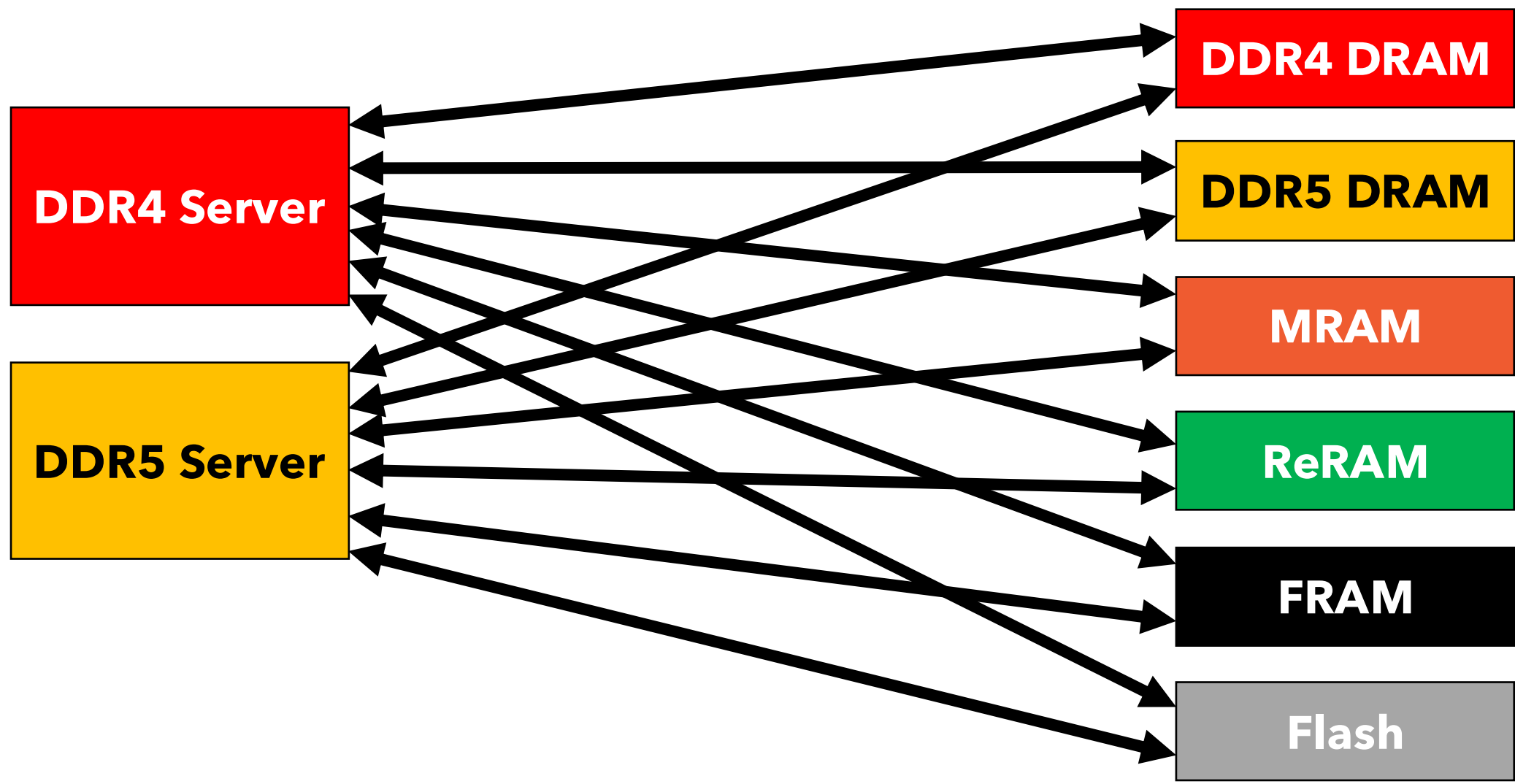
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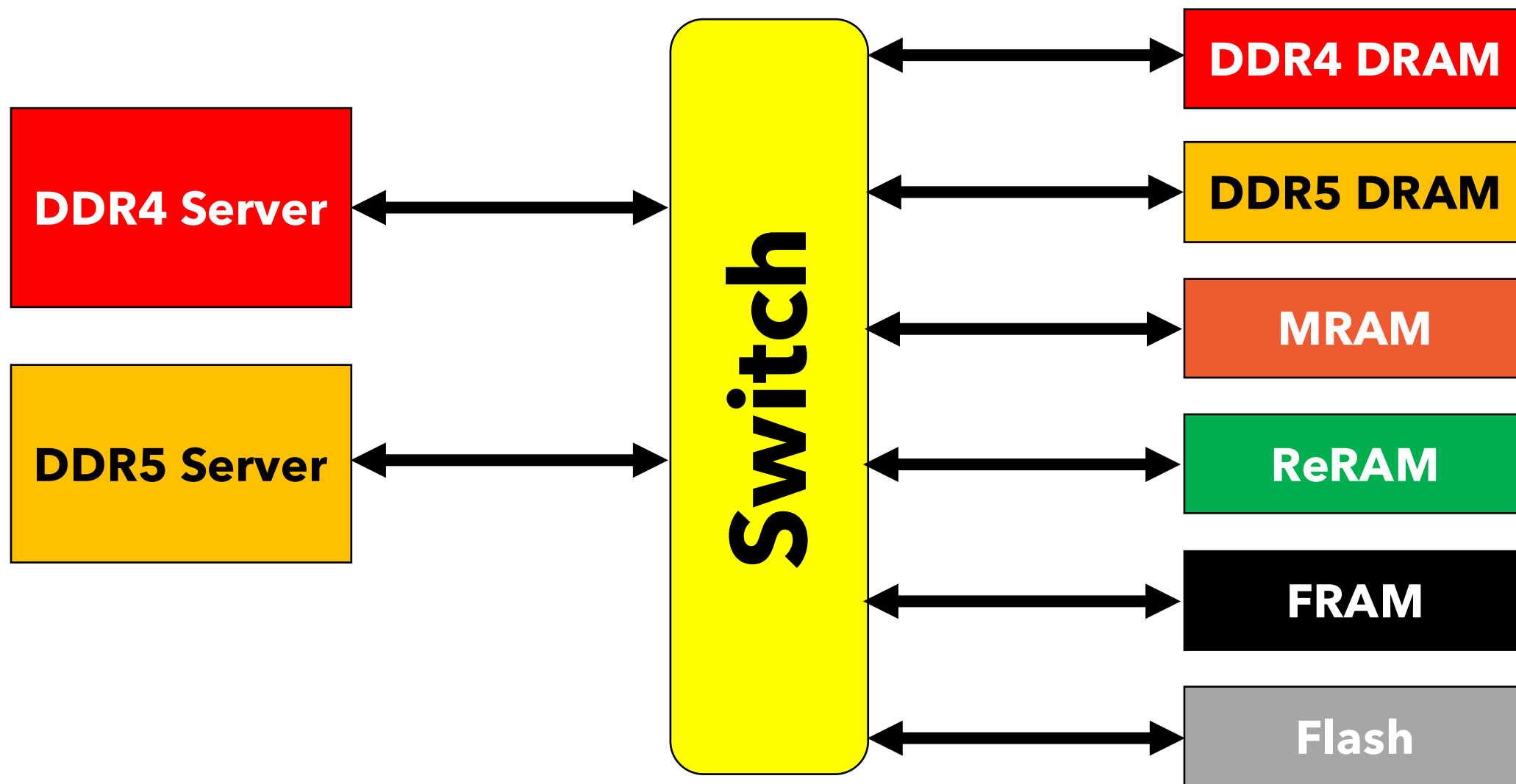
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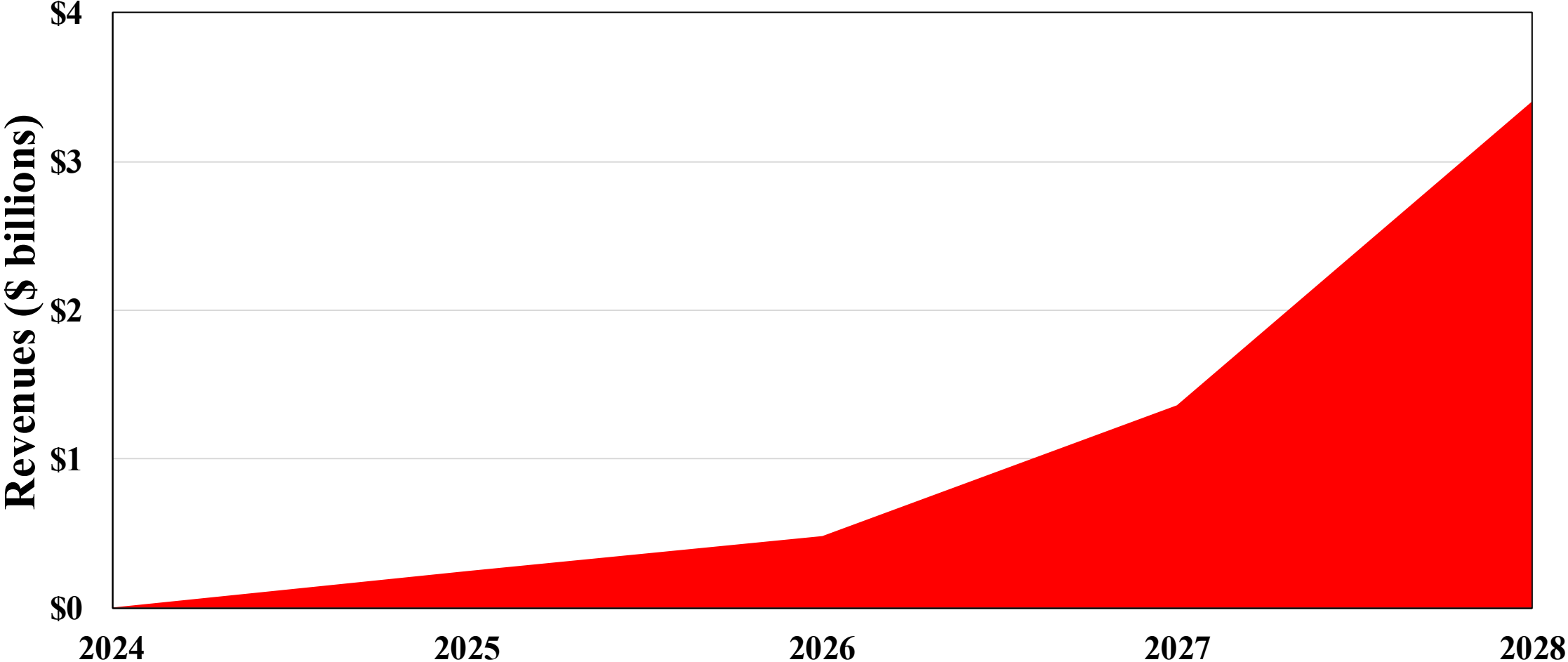


# CXL Supports Any Memory, Volatile or Persistent



# CXL Forecast

## CXL Revenue Forecast

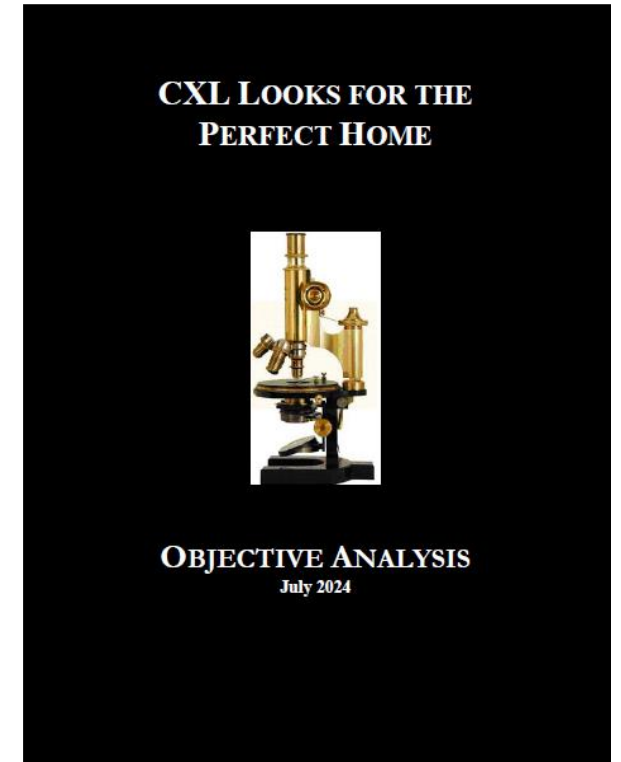


# Long-Term Impact

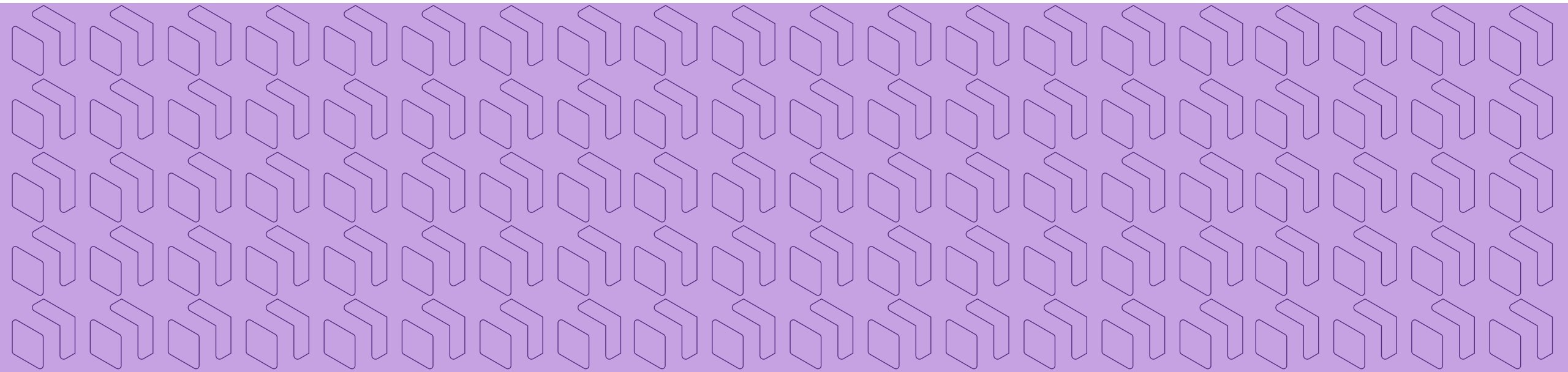
- Re-thinking system architecture
  - Disaggregated memory
  - Processor arrays with mesh networks
  - Memory agnostic
- Better memory bandwidth & size vs. worse latency
  - Design-arounds will optimize for this

# Report: *CXL Looks for the Perfect Home*

- Exhaustive report from Objective Analysis
  - Covers all perspectives
    - Where CXL is useful, and where it isn't
    - Demand drivers for CXL DRAM modules
    - Opportunities outside of DRAM
    - Forecast (Revenues, units, ASP)
  - Available for immediate download:
- [Objective-Analysis.com/reports](https://Objective-Analysis.com/reports)



# Market Sizing

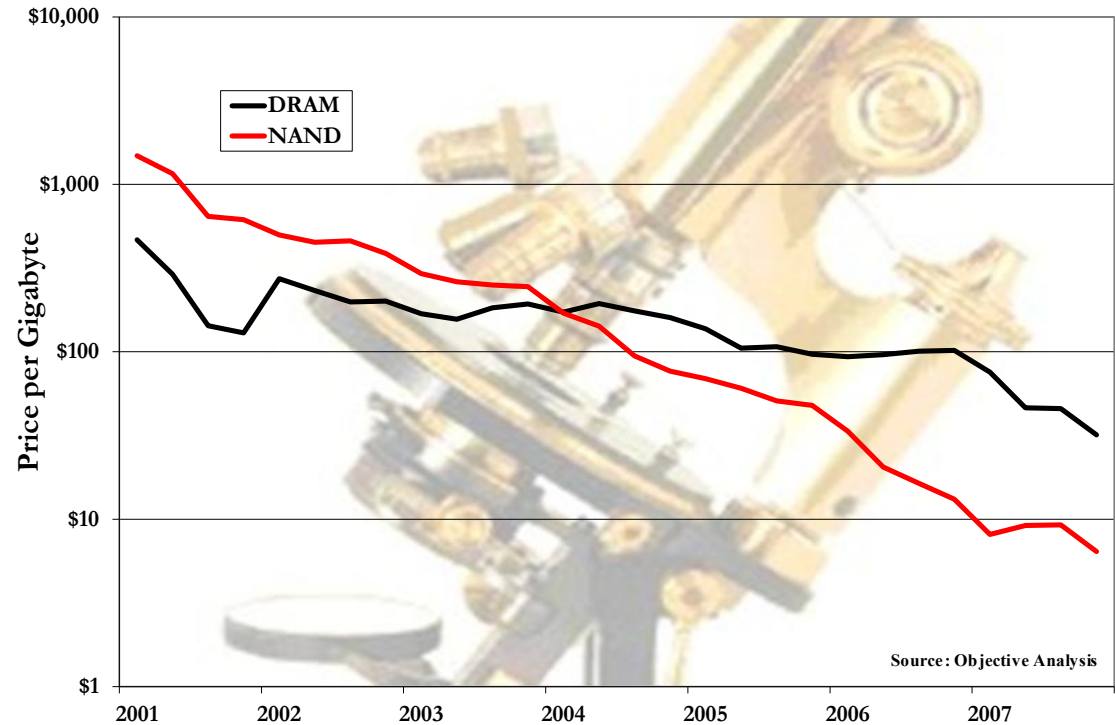


# Market Factors

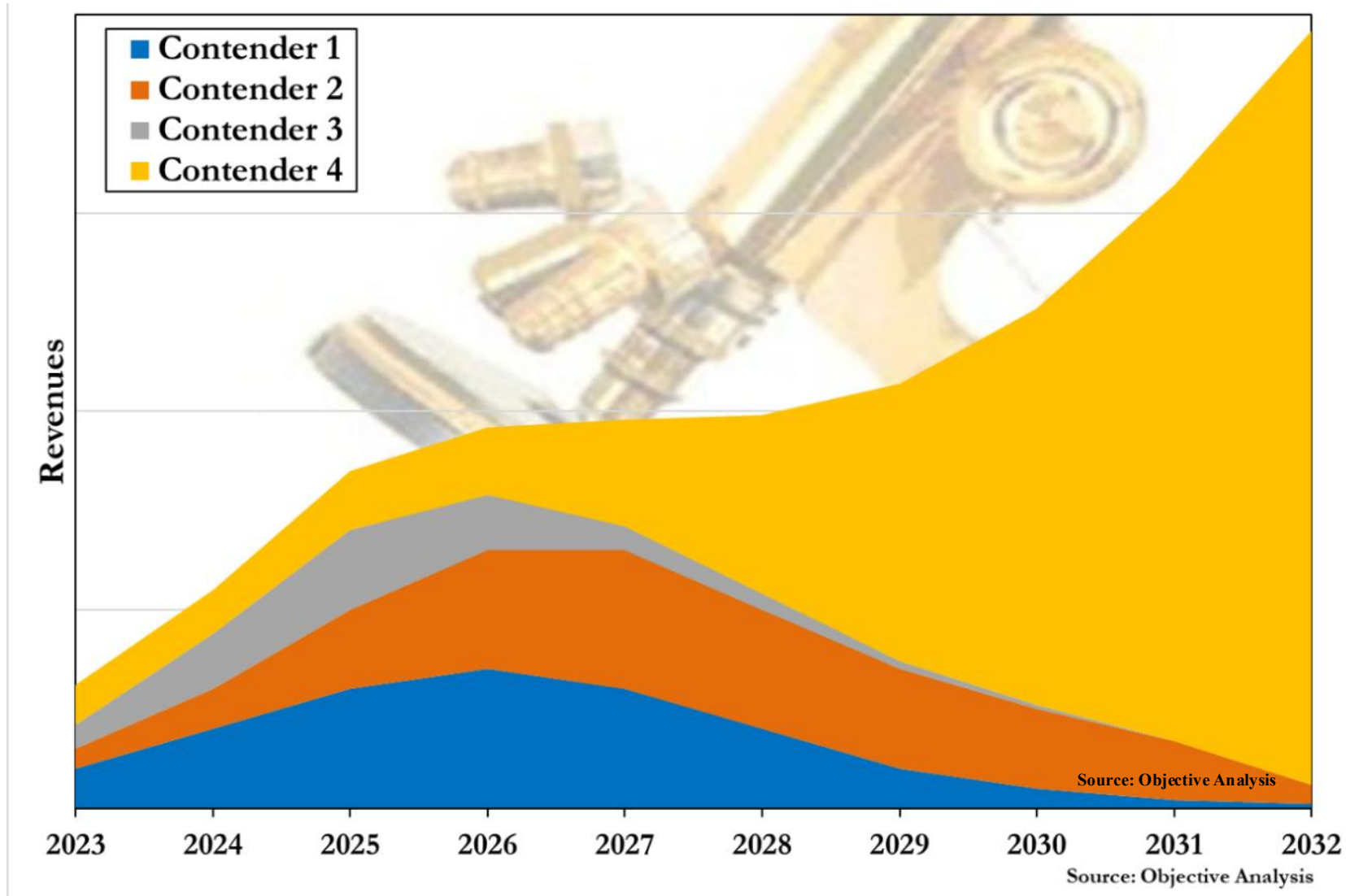
- Drivers: Why will it grow?
- Types: Embedded vs. Stand-Alone (Discrete) devices
- Economies of Scale
- One or Many Winners?

# Economies of Scale

- A smaller die size doesn't guarantee a cheaper part
- Wafer volume is critical
- Pricing determines sales volume
- Sales volume determines production cost
- It's a chicken-and-egg problem



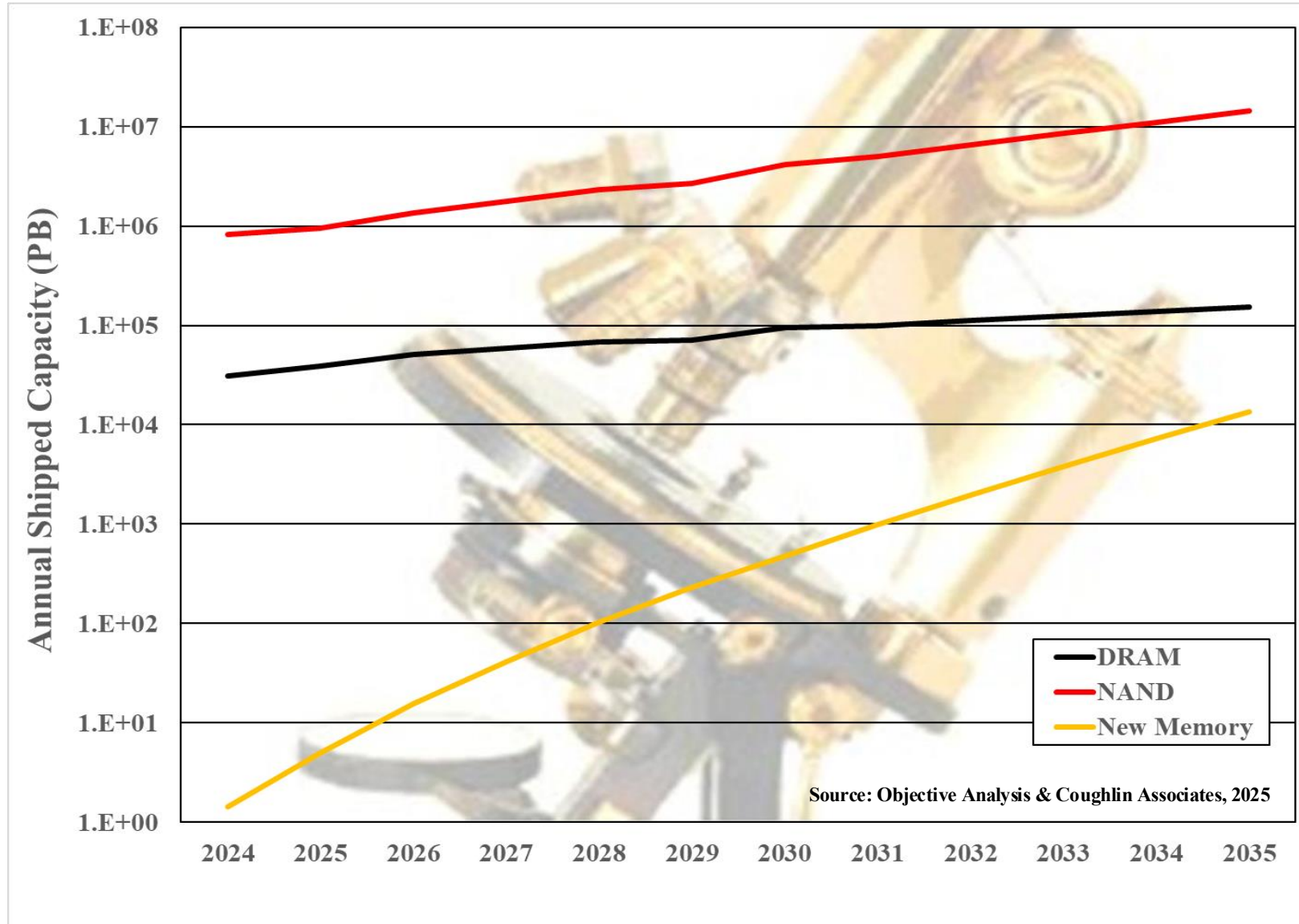
# One or Many Winners?



# Forecast Assumptions

- Embedded memories drive early volumes
- Wafer volume drives economies of scale
  - Opens new markets for stand-alone chips
- Low price always wins out over better features
  - NOR/SRAM cell phones vs. NAND/DRAM
- We take no position on which technology will win out
  - Our only expectation is that only one will succeed in a big way

# Rapid New Memory Terabyte Growth



# Report: *New Memory – Not Just for AI*

- ✦ Exhaustive examination of new memory technologies
  - ✦ 326 pages
  - ✦ 219 Figures
  - ✦ 36 Tables
  - ✦ 175 company profiles
- ✦ Technologies, forecasts, tool use, business issues, situation analysis

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# Q&A

